ULTRA-COMPACT UNCOOLED
THERMAL CORE

Xenics
EXOSENS GROUP

MicroCube 640

EXTREMELY SMALL THERMAL CORE WITH 12 µm PIXEL PITCH

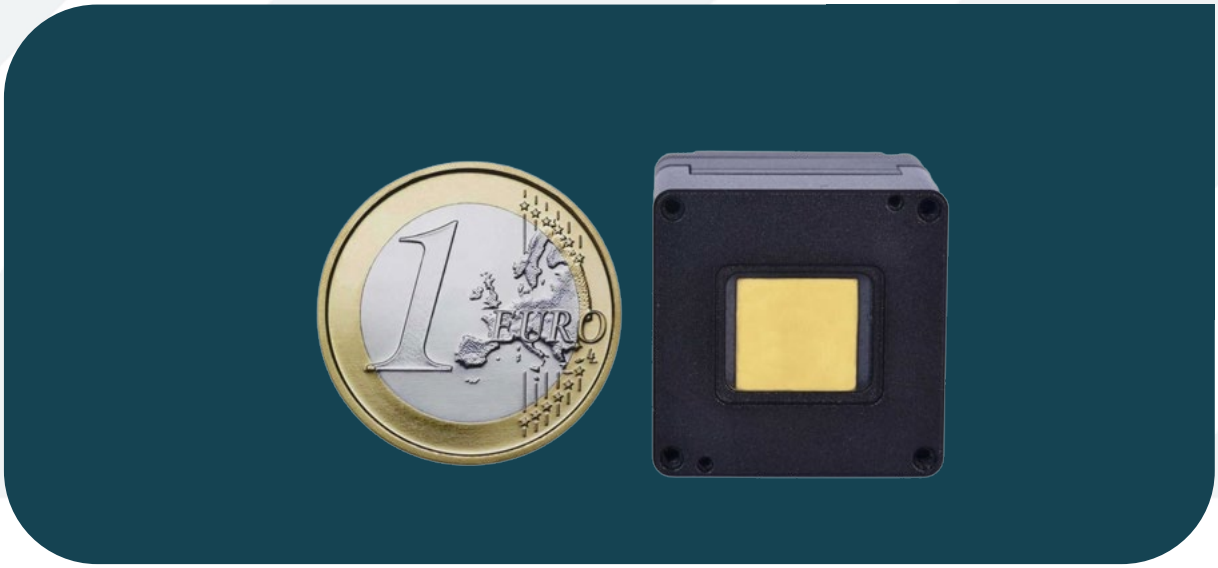
KEY FEATURES

- **EASY INTEGRATION**
- **HIGH SENSITIVE CAMERA CORE IN LWIR**
- **OPTIMIZED SIZE, WEIGHT & POWER**

The latest generation of thermal cores in 12µm pixel pitch feature true SWaP design and cover main standard interfaces.

Size, weight and power altogether make this European-made thermal core the ideal candidate for all applications where consumption and/or footprint are key factors, namely UAVs, UGVs and robot-type platforms, as well as handheld devices and all battery-powered equipment.

MicroCube 640



KEY PERFORMANCES

Sensor	Micro-bolometer technology
Resolution / Pixel Pitch	640 x 480 pixels / 12 µm
Spectral Range	8 – 14 µm
Max NETD (F/1 ; 300K ; 30 Hz)	< 50 mK or < 40 mK
Operating temperature range	-40°C to +70°C
Power consumption (DF40)	< 1.2 W
Qualification	Industrial (Standard grade)

FUNCTIONS & INTERFACES

Image processing	BPC (Bad Pixel Correction), NUC (Non Uniformity Correction), Shutterless NUC
Image optimisation	AGC (Automatic Gain Control)
Output options	MIPI-CSI, DF40
Dimensions (L x W x H) (DF40)	22.0 x 22.0 x 26.8 mm^3
Weight (DF40)	< 25 g

PRODUCT SELECTOR GUIDE

XEN-000933 [MicroCube 50 mK (9Hz)]	XEN-000934 [MicroCube 50 mK (60Hz)]
XEN-000935 [MicroCube 40 mK (9Hz)]	XEN-000936 [MicroCube 40 mK (60Hz)]

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